

L Number	Hits	Search Text	DB	Time stamp
-	2	("5489966").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/01 14:09
-	56197	semiconductor.as.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/01 14:10
-	73	semiconductor-leading-edge-technologies.as.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/01 14:17
-	2	jp-2001006107-\$.did.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/01 14:23
-	0	jp-20013075598-\$.did.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/01 14:19
-	0	jp-13006107-\$.did.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/01 14:21
-	0	jp-133075598-\$.did.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/01 14:21
-	4	kim-jeong-yeal.in.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/01 14:24
-	409	(250/201.2).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/03 12:29
-	677	(250/204).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/03 12:29
-	934	(250/548).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/03 12:30
-	562	(250/559.45).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/03 12:30

-	1981	(355/53).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/03 12:32
-	1204	(355/55).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/03 13:53
-	959	(355/68).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/03 13:53
-	578	wafer and 250/201.2,204,548,559.45.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/03 14:02
-	13	wafer and 250/204.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/03 13:55
-	481	wafer and 250/548.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/03 13:55
-	56	wafer and 250/559.45.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/03 13:55
-	37	wafer and 250/201.2.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/03 13:55
-	111	wafer with edge and 250/201.2,204,548,559.45.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/03 14:14
-	165	wafer with edge and 355/53,55,68.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/03 14:12
-	17	wafer with edge with exposure and 250/201.2,204,548,559.45.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/03 14:21
-	64	wafer with edge with exposure and 355/53,55,68.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/03 14:21

-	6	wafer with edge with exposure with light and 250/201.2,204,548,559.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/03 14:21
-	37	wafer with edge with exposure with light and 355/53,55,68.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/03 14:32